

# SN75ALS1177, SN75ALS1178 Dual Differential Drivers and Receivers

## 1 Features

- Meet or exceed standards TIA/EIA-422-B and TIA/EIA-485-A
- Designed for multipoint bus transmission on long bus lines in noisy environments
- Low supply-current requirement 50mA maximum
- Driver positive-and negative-current limiting
- Driver common-mode output voltage range of -7V to 12V
- Thermal shutdown protection driver 3-state outputs active-high enable
- Receiver common-mode input voltage range of -12V to 12V
- Receiver input sensitivity:  $\pm 200\text{mV}$
- Receiver hysteresis: 50mV typical
- Receiver high input impedance: 12k $\Omega$  minimum
- Receiver 3-state outputs active-low enable for SN75ALS1177 only
- Operate from single 5V supply

## 2 Applications

- [Motor Drives](#)
- [Factory Automation](#)
- [Building Automation](#)

## 3 Description

The SN75ALS1177 and SN75ALS1178 dual differential drivers and receivers are integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. The devices are designed for balanced transmission lines, and meet standards TIA/EIA-422-B and TIA/EIA-485-A.

The SN75ALS1177 combines dual 3-state differential line drivers and dual 3-state differential input line receivers, both of which operate from a single 5V power supply. The drivers and receivers have active-high and active-low enables, respectively, which can be externally connected together to function as direction control. The SN75ALS1178 drivers each have an individual active-high enable. Fail-safe design ensures that when the receiver inputs are open, the receiver outputs are always high.

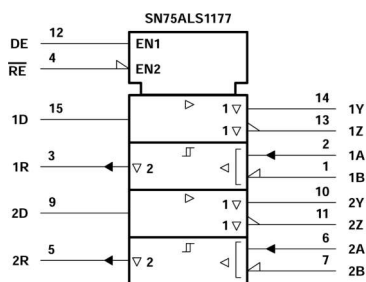
The SN75ALS1177 and SN75ALS1178 are characterized for operation from 0°C to 70°C.

### Package Options

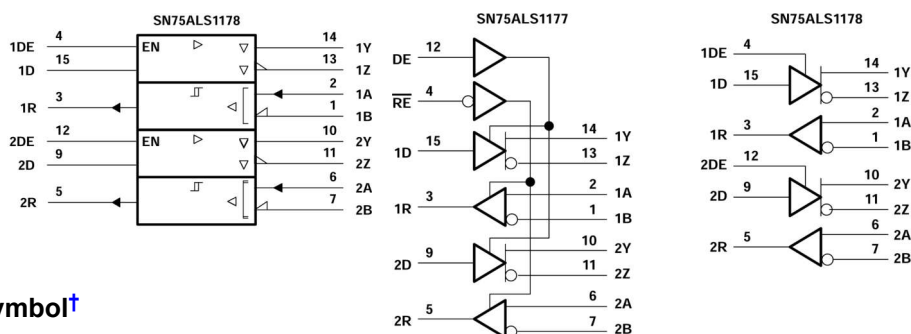
PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>
SN75ALS1177	SOP (NS, 16)	10.2mm × 7.8mm
SN75ALS1178	PDIP (N, 16)	19.3mm × 9.4mm

(1) For more information, see [Section 10](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Logic Symbol<sup>†</sup>



Logic Diagram (Positive Logic)

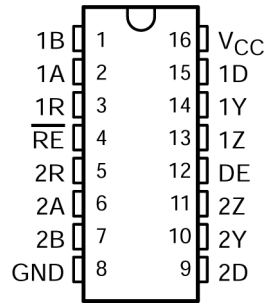
<sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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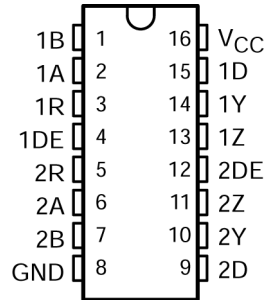
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## 4 Pin Configuration and Functions



**Figure 4-1. SN75ALS1177: N or NS Package  
(Top View)**

NAME	PIN		TYPE	DESCRIPTION
	SO	TSSOP		
1A	2	2	I	RS422 differential input (non-inverting) to receiver 1
2A	6	6	I	RS422 differential input (non-inverting) to receiver 2
1B	1	1	I	RS422 differential input (inverting) to receiver 1
2B	7	7	I	RS422 differential input (inverting) to receiver 2
1D	15	15	I	Logic data input to RS422 driver 1
2D	9	9	I	Logic data input to RS422 driver 2
DE	12	12	I	Driver enable (active high)
GND	8	8	—	Device ground pin
1R	3	3	O	Logic data output of RS422 receiver 1
2R	5	5	O	Logic data output of RS422 receiver 2
RE	4	4	I	Receiver enable pin (active low)
V <sub>CC</sub>	16	16	—	Power supply
1Y	14	14	O	RS-422 differential (non-inverting) driver output 1
2Y	10	10	O	RS-422 differential (non-inverting) driver output 2
1Z	13	13	O	RS-422 differential (inverting) driver output 1
2Z	11	11	O	RS-422 differential (inverting) driver output 2



**Figure 4-2. SN75ALS1178: N or NS Package (Top View)**

PINT			TYPE	DESCRIPTION
NAME	SO	TSSOP		
1A	2	2	I	RS422 differential input (non-inverting) to receiver 1
2A	6	6	I	RS422 differential input (non-inverting) to receiver 2
1B	1	1	I	RS422 differential input (inverting) to receiver 1
2B	7	7	I	RS422 differential input (inverting) to receiver 2
1D	15	15	I	Logic data input to RS422 driver 1
2D	9	9	I	Logic data input to RS422 driver 2
1DE	4	4	I	Driver 1 enable (active high)
2DE	12	12	I	Driver 2 enable (active high)
GND	8	8	—	Device ground
1R	3	3	O	Logic data output of RS422 receiver 1
2R	5	5	O	Logic data output of RS422 receiver 2
V <sub>CC</sub>	16	16	—	Power supply
1Y	14	14	O	RS-422 differential (non-inverting) driver output 1
2Y	10	10	O	RS-422 differential (non-inverting) driver output 2
1Z	13	13	O	RS-422 differential (non-inverting) driver output 1
2Z	11	11	O	RS-422 differential (non-inverting) driver output 2

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage, (see <sup>(2)</sup> )		7	V
V <sub>I</sub>	Input voltage, (DE, RE, and D inputs)		7	V
V <sub>O</sub>	Output voltage range, drivers	-9	14	V
	Input voltage range, receiver	-14	14	V
	Receiver differential-input voltage range, (see <sup>(3)</sup> )	-14	14	V
	Receiver low-level output current		50	mA
	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		260	°C
T <sub>stg</sub>	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential input voltage, are with respect to the network ground terminal.
- (3) Differential input voltage is measured at the noninverting terminal with respect to the inverting terminal.

### 5.2 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4.75	5	5.25	V
V <sub>ID</sub>	Differential input voltage			±12	V
V <sub>OC</sub>	Common-mode output voltage	-7 <sup>(1)</sup>		12	V
V <sub>IC</sub>	Common-mode input voltage			±12	V
V <sub>IH</sub>	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>OH</sub>	High-level output current	Driver		-60	mA
		Receiver		-400	µA
I <sub>OL</sub>	Low - level out output current	Driver		60	mA
		Receiver		8	mA
T <sub>A</sub>	Operating free-air temperature	0		70	°C

- (1) The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode output and threshold voltage level only.

### 5.3 Thermal Information

THERMAL METRIC <sup>(1)</sup>		PDIP (N)	SO (NS)	UNIT
		16 Pins	16 Pins	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance (see <sup>(2)</sup> )	60.6	88.5	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	48.1	46.2	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	40.6	50.7	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	27.5	13.5	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	40.3	50.3	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.

## 5.4 Driver Section

### 5.4.1 Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>IK</sub>	Input clamp voltage	I <sub>I</sub> = -18 mA					-1.5	V
V <sub>OH</sub>	High-level output voltage	V <sub>IH</sub> = 2V,	V <sub>IL</sub> = 0.8V,	I <sub>OH</sub> = -33mA		3.3		V
V <sub>OL</sub>	Low-level output voltage	V <sub>IH</sub> = 2V,	V <sub>IL</sub> = 0.8V,	I <sub>OL</sub> = 33mA		1.1		V
V <sub>OD1</sub>	Differential output voltage	I <sub>O</sub> = 0			1.5		6	V
V <sub>OD2</sub>	Differential output voltage	V <sub>CC</sub> = 5V,	R <sub>L</sub> = 100Ω,	See Figure 6-1	1/2V <sub>OD1</sub> or 2 <sup>(2)</sup>			V
		R <sub>L</sub> = 54Ω,	See Figure 6-1		1.5	2.5	5	
V <sub>OD3</sub>	Differential output voltage	See Note 4			1.5		5	V
Δ V <sub>OD</sub>	Change in magnitude of differential output voltage (see Note 5)	R <sub>L</sub> = 54Ω or 100Ω,		See Figure 6-1			±0.2	V
V <sub>OC</sub>	Common-mode output voltage	R <sub>L</sub> = 54Ω or 100Ω,		See Figure 6-1	-1 <sup>(3)</sup>		3	V
Δ V <sub>OC</sub>	Change in magnitude of common-mode output voltage (see Note 5)	R <sub>L</sub> = 54Ω or 100Ω,		See Figure 6-1			±0.2	V
I <sub>O(OFF)</sub>	Output current with power off	V <sub>CC</sub> = 0,	V <sub>O</sub> = -7V to 12V				±100	μA
I <sub>OZ</sub>	High-impedance-state output current	V <sub>O</sub> = -7V to 12V					±100	μA
I <sub>IH</sub>	High-level input current	V <sub>IH</sub> = 2.7V					100	μA
I <sub>IL</sub>	Low-level input current	V <sub>IL</sub> = 0.4V					-100	μA
I <sub>OS</sub>	Short-circuit output current	V <sub>O</sub> = -7V					-250	mA
		V <sub>O</sub> = V <sub>CC</sub>					250	
		V <sub>O</sub> = 12V					250	
		V <sub>O</sub> = 0V					150	
I <sub>CC</sub>	Supply current (total package)	No load	Outputs enabled			35	50	mA
			Outputs disabled			20	50	

(1) All typical values are at V<sub>CC</sub> = 5V and T<sub>A</sub> = 25°C.

(2) The minimum V<sub>OD2</sub> with a 100Ω load is either 1/2 V<sub>OD1</sub> or 2V, whichever is greater.

(3) The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode output and threshold voltage levels only.

(4) See TIA/EIA-485-A Figure 6-3.5, test termination measurement 2.

(5) Δ|V<sub>OD</sub>| and Δ|V<sub>OC</sub>| are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input is changed from a high level to a low level.

### 5.4.2 Switching Characteristics

at V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, high- to low-level output	R <sub>L</sub> = 60Ω, C <sub>L1</sub> = C <sub>L2</sub> = 100pF, See Figure 6-3			9	15	22	ns
t <sub>PHL</sub>	Propagation delay time, low- to high-level output	R <sub>L</sub> = 60Ω, C <sub>L1</sub> = C <sub>L2</sub> = 100pF, See Figure 6-3			9	15	22	ns
t <sub>sk</sub>	Output-to-output skew	R <sub>L</sub> = 60Ω, C <sub>L1</sub> = C <sub>L2</sub> = 100pF, See Figure 6-3			0	2	8	ns
t <sub>PZH</sub>	Output enable time to high level	C <sub>L</sub> = 100pF,	See Figure 6-4		30	35	50	ns
t <sub>PZL</sub>	Output enable time to low level	C <sub>L</sub> = 100pF,	See Figure 6-5		5	15	25	ns
t <sub>PHZ</sub>	Output disable time from high level	C <sub>L</sub> = 15pF,	See Figure 6-4		7	15	30	ns
t <sub>PLZ</sub>	Output disable time from low level	C <sub>L</sub> = 15pF,	See Figure 6-5		7	15	30	ns

## 5.5 Receiver Section

### 5.5.1 Electrical Characteristics

over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage		V <sub>O</sub> = 2.7V, I <sub>O</sub> = -0.4mA			0.2	V
V <sub>IT-</sub>	Negative-going input threshold voltage		V <sub>O</sub> = 0.5V, I <sub>O</sub> = 8mA	-0.2 <sup>(2)</sup>			V
V <sub>hys</sub>	Input hysteresis voltage (V <sub>IT+</sub> - V <sub>IT-</sub> )				50		mV
V <sub>IK</sub>	Enable input clamp voltage	SN75ALS1177	I <sub>I</sub> = -18mA			-1.5	V
V <sub>OH</sub>	High-level output voltage		V <sub>ID</sub> = 200mV, I <sub>OH</sub> = -400μA, See <a href="#">Figure 6-2</a>	2.7			V
V <sub>OL</sub>	Low-level output voltage		V <sub>ID</sub> = 200mV, I <sub>OL</sub> = 8mA, See <a href="#">Figure 6-2</a>			0.45	V
I <sub>OZ</sub>	High-impedance-state output current	SN75ALS1177	V <sub>O</sub> = 0.4V to 2.4V			±20	μA
I <sub>I</sub>	Line input current (see <a href="#">Note 6</a> )		Other input at 0V	V <sub>I</sub> = 12V		1	mA
				V <sub>I</sub> = -7V		-0.8	
I <sub>IH</sub>	High-level input current, $\overline{RE}$	SN75ALS1177	V <sub>IH</sub> = 2.7V			20	μA
I <sub>IL</sub>	Low-level input current, $\overline{RE}$	SN75ALS1177	V <sub>IL</sub> = 0.4V			-100	μA
r <sub>i</sub>	Input resistance			12			kΩ
I <sub>OS</sub>	Short-circuit output current		V <sub>O</sub> = 0V, See <a href="#">Note 7</a>	-15		-85	mA
I <sub>CC</sub>	Supply current (total package)		No load, outputs enabled		35	50	mA

- (1) All typical values are at V<sub>CC</sub> = 5V and T<sub>A</sub> = 25°C.
- (2) The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode output and threshold voltage levels only.
- (3) Refer to TIA/EIA-422-B, TIA/EIA-423-A, and TIA/EIA-485-A for exact conditions.
- (4) Not more than one output should be shorted at a time.

### 5.5.2 Switching Characteristics

at V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low- to high-level output		C <sub>L</sub> = 15pF, See <a href="#">Figure 6-6</a>	15	25	37	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level output		C <sub>L</sub> = 15pF, See <a href="#">Figure 6-6</a>	15	25	37	ns
t <sub>PZH</sub>	Output enable time to high level	SN75ALS1177	C <sub>L</sub> = 100pF, See <a href="#">Figure 6-7</a>	10	20	30	ns
t <sub>PZL</sub>	Output enable time to low level	SN75ALS1177	C <sub>L</sub> = 100pF, See <a href="#">Figure 6-7</a>	10	20	30	ns
t <sub>PHZ</sub>	Output disable time from high level	SN75ALS1177	C <sub>L</sub> = 15pF, See <a href="#">Figure 6-7</a>	3.5	12	16	ns
t <sub>PLZ</sub>	Output disable time from low level	SN75ALS1177	C <sub>L</sub> = 15pF, See <a href="#">Figure 6-7</a>	5	12	16	ns

## 6 Parameter Measurement Information

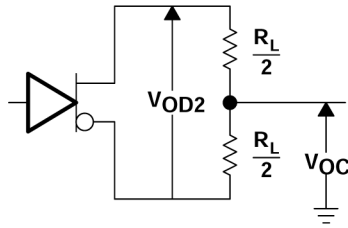


Figure 6-1. Driver Test Circuit,  $V_{OD}$  and  $V_{OC}$

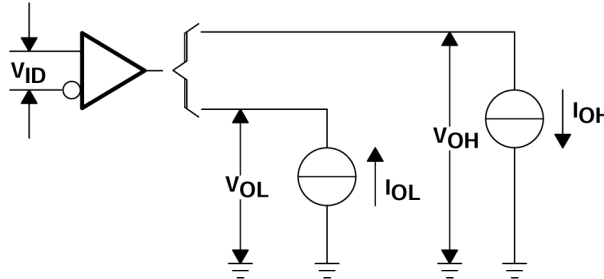
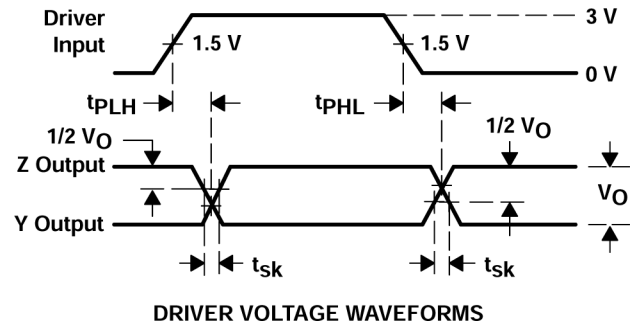
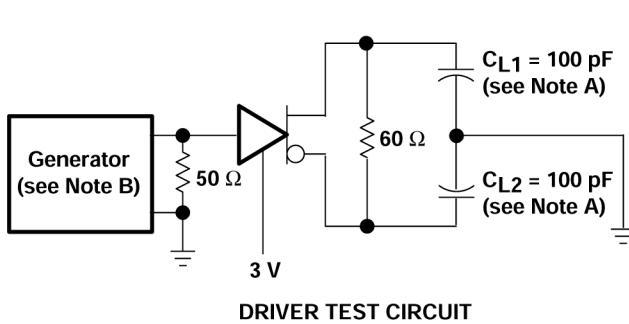
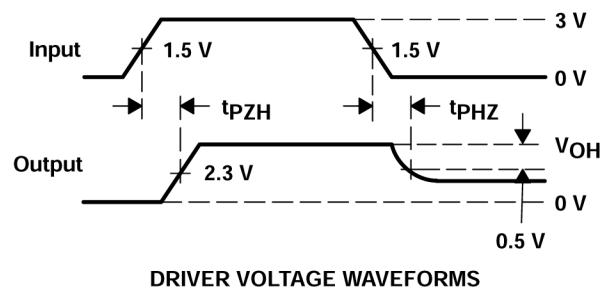
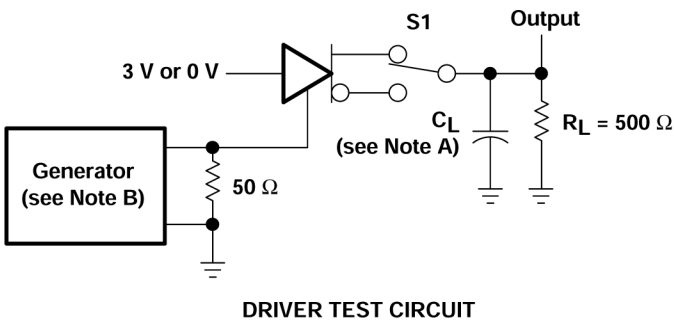


Figure 6-2. Receiver Test Circuit,  $V_{OH}$  and  $V_{OL}$



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $PRR \leq 1\text{MHz}$ , 50% duty cycle,  $t_r \leq 10\text{ns}$ ,  $t_f \leq 10\text{ns}$ .

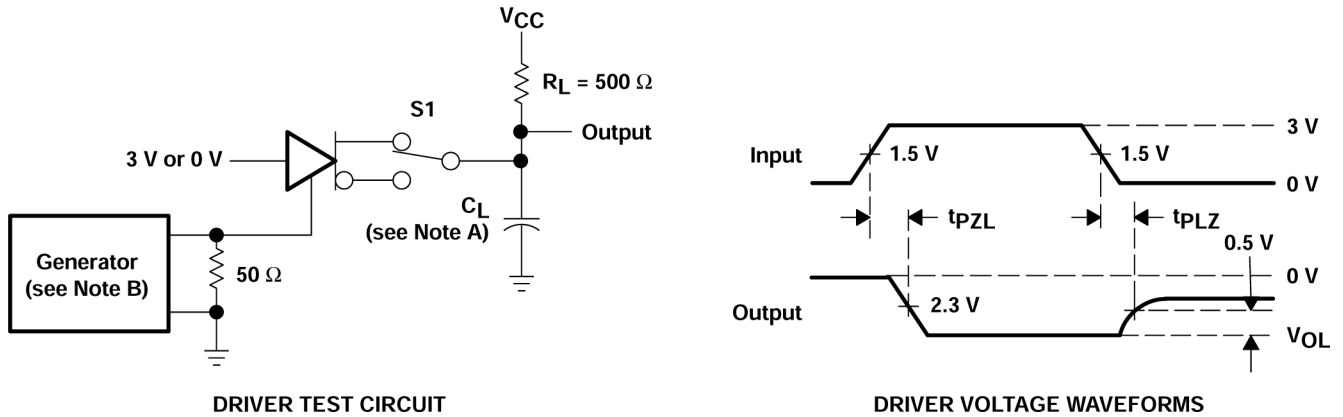
Figure 6-3. Driver Propagation Delay Times



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $PRR \leq 1\text{MHz}$ , 50% duty cycle,  $t_r \leq 10\text{ns}$ ,  $t_f \leq 10\text{ns}$ .

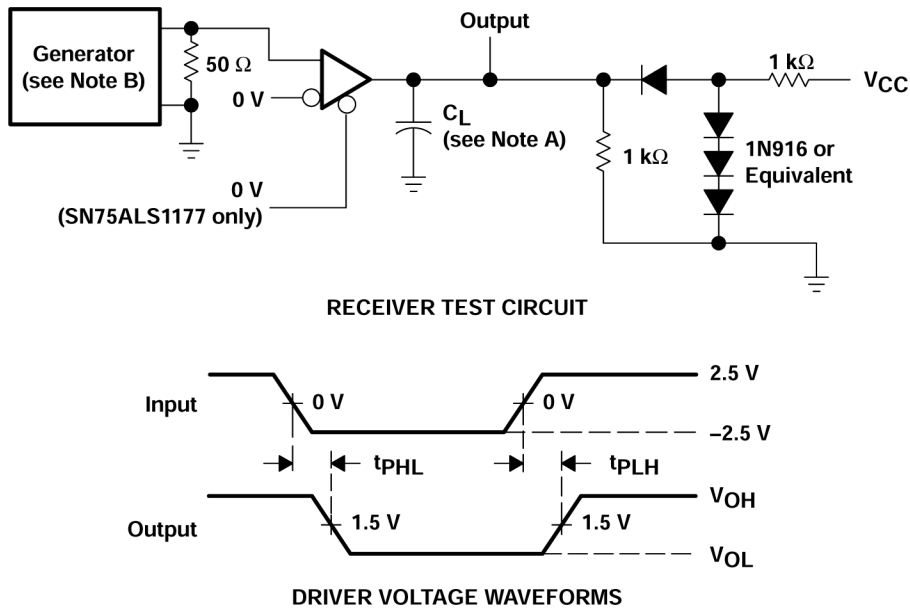
Figure 6-4. Driver Enable and Disable Times





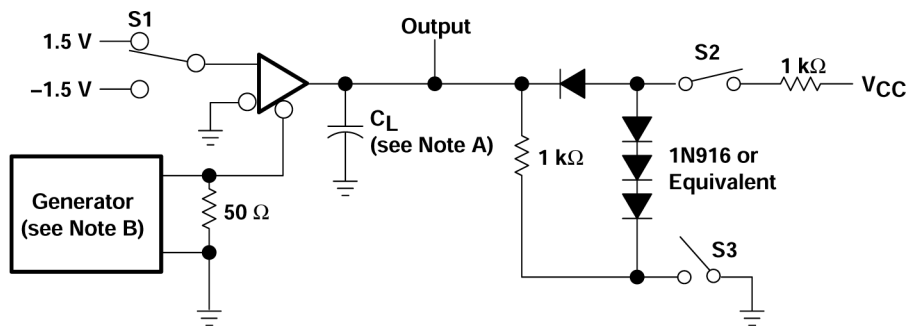
- A. C<sub>L</sub> includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR ≤ 1MHz, 50% duty cycle, t<sub>r</sub> ≤ 10ns, t<sub>f</sub> ≤ 10ns.

Figure 6-5. Driver Enable and Disable Times

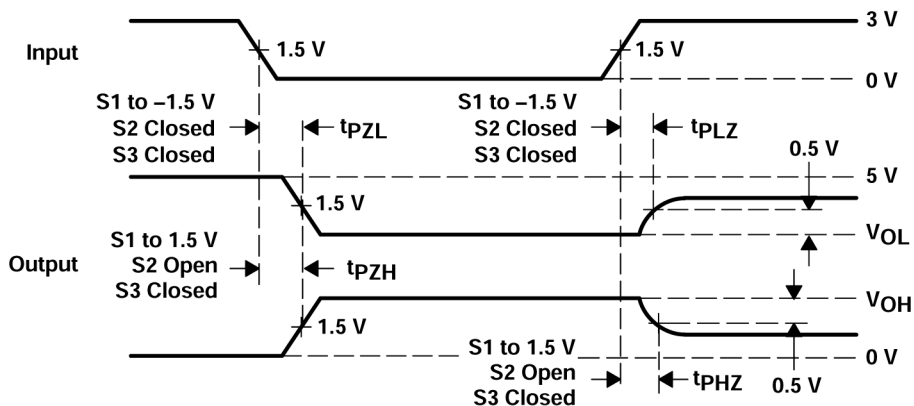


- A. C<sub>L</sub> includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR ≤ 1MHz, 50% duty cycle, t<sub>r</sub> ≤ 10ns, t<sub>f</sub> ≤ 10ns.

Figure 6-6. Receiver Propagation Delay Times



RECEIVER TEST CIRCUIT



RECEIVER VOLTAGE WAVEFORMS

- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $PRR \leq 1\text{MHz}$ , 50% duty cycle,  $t_r \leq 10\text{ns}$ ,  $t_f \leq 10\text{ns}$ .

**Figure 6-7. Receiver Output Enable and Disable Times**

## 7 Detailed Description

### 7.1 Device Functional Modes

Table 7-1. SN75ALS1177, SN75ALS1178 Functional Table (Each Driver)

INPUT D	ENABLE DE	OUTPUTS <sup>(1)</sup>	
		Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z

Table 7-2. SN75ALS1177 Functional Table (Each Receiver)

DIFFERENTIAL A-B	ENABLE $\overline{RE}$ <sup>(1)</sup>	OUTPUT Y <sup>(1)</sup>
$V_{ID} \geq 0.2V$	L	H
$-0.2V < V_{ID} < 0.2V$	L	?
$V_{ID} \leq -0.2V$	L	L
X	H	Z
Open	L	H

Table 7-3. SN75ALS1178 Functional Table (Each Receiver)

DIFFERENTIAL A-B	OUTPUT Y <sup>(1)</sup>
$V_{ID} \geq 0.2V$	H
$-0.2V < V_{ID} < 0.2V$	?
$V_{ID} \leq -0.2V$	L
Open	H

(1) H = High level, L = Low level, ? = Indeterminate, X = Irrelevant, Z = High impedance (off)

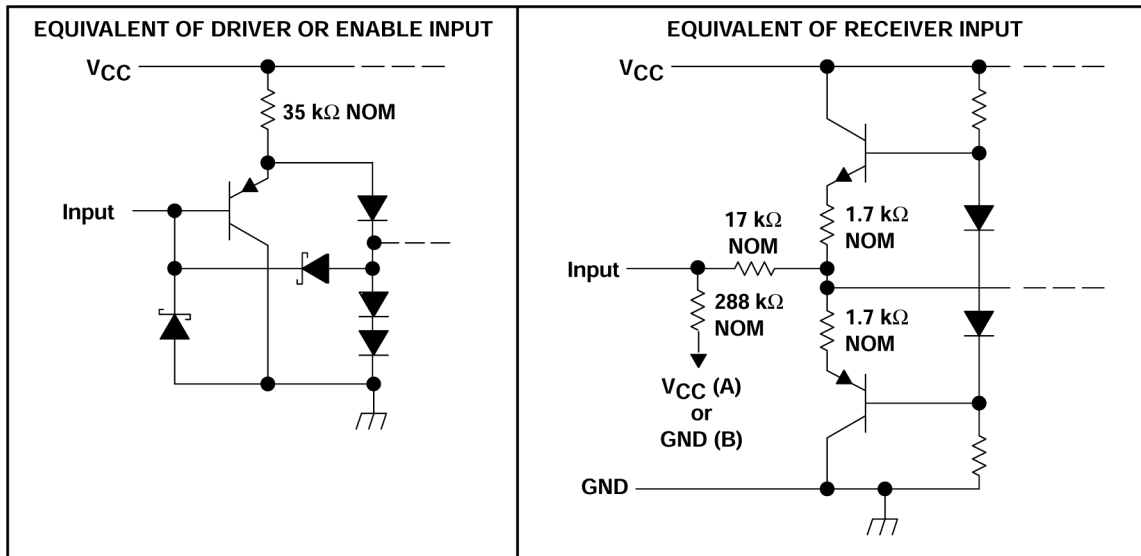


Figure 7-1. Equivalent Schematics

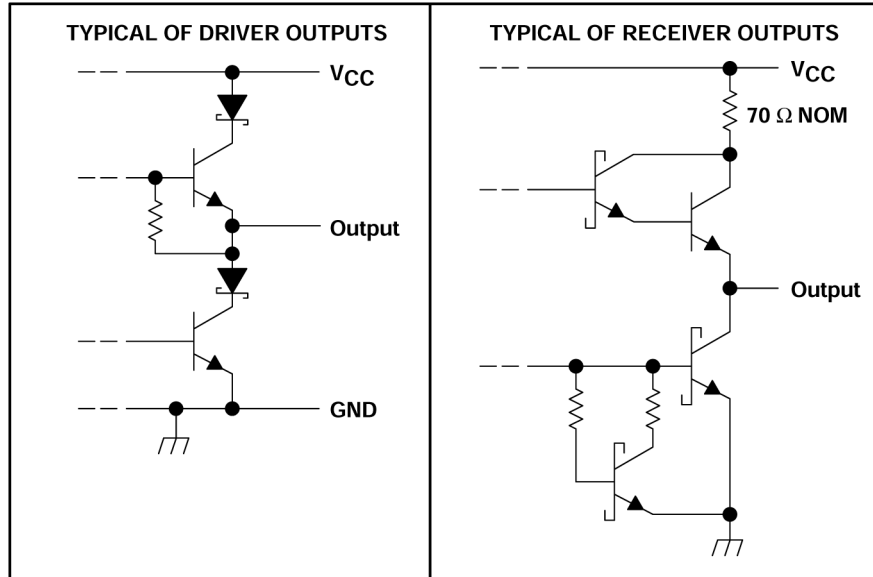


Figure 7-2. Schematics of Outputs

## 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 8.1 Documentation Support

### 8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 8.3 Support Resources

[E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 8.4 Trademarks

E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 9 Revision History

<b>Changes from Revision B (February 2001) to Revision C (February 2024)</b>	<b>Page</b>
• Changed the numbering format for tables, figures, and cross-references throughout the document.....	<b>1</b>

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75ALS1177N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75ALS1177N	<a href="#">Samples</a>
SN75ALS1177NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS1177	<a href="#">Samples</a>
SN75ALS1178N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75ALS1178N	<a href="#">Samples</a>
SN75ALS1178NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS1178	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS1177NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75ALS1177NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75ALS1178NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75ALS1178NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS1177NSR	SO	NS	16	2000	356.0	356.0	35.0
SN75ALS1177NSR	SO	NS	16	2000	353.0	353.0	32.0
SN75ALS1178NSR	SO	NS	16	2000	353.0	353.0	32.0
SN75ALS1178NSR	SO	NS	16	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN75ALS1177N	N	PDIP	16	25	506	13.97	11230	4.32
SN75ALS1178N	N	PDIP	16	25	506	13.97	11230	4.32

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



# PACKAGE OUTLINE

## NS0016A

### SOP - 2.00 mm max height

SOP



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#### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

# EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:7X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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